

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

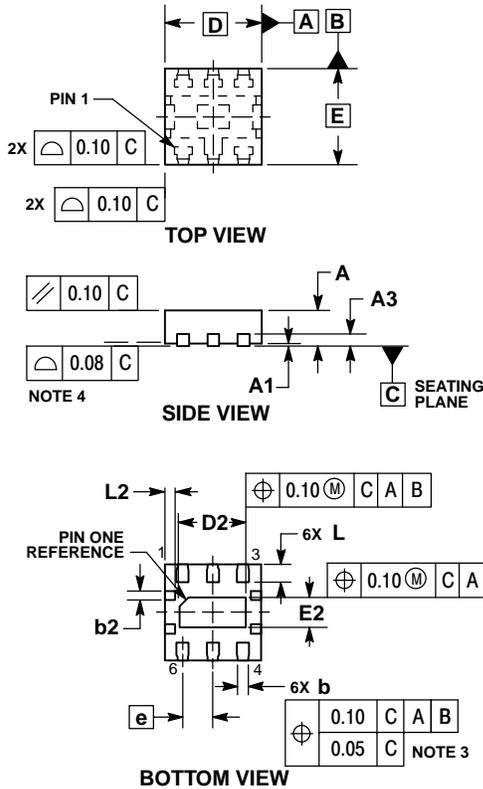
ON Semiconductor®



SCALE 2:1

CUDFN6 1.6x1.6, 0.5P
CASE 505AL
ISSUE A

DATE 09 FEB 2017



NOTES:

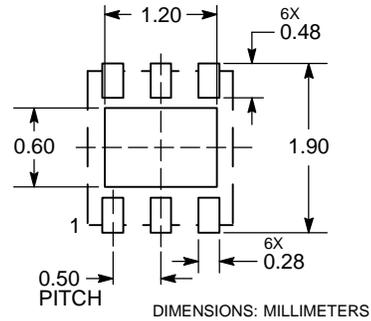
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.10 AND 0.20MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.55	0.65
A1	0.00	0.05
A3	0.20 REF	
b	0.15	0.25
b2	0.15 REF	
D	1.60 BSC	
D2	1.05	1.15
E	1.60 BSC	
E2	0.45	0.55
e	0.50 BSC	
L	0.25	0.35
L2	0.17 REF	

GENERIC MARKING DIAGRAM*

*No marking due to clear package

RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON89262F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	CUDFN6, 1.6X1.6, 0.5P	PAGE 1 OF 2

